



Product Change Notification



Product Group: Vishay Siliconix/ March 2nd, 2017/PCN-SIL-4022017

Additional Back End Capacity for Vishay Siliconix ICs in TDFN4 Package

DESCRIPTION OF CHANGE: To meet increasing demand, Vishay Siliconix has expanded capacity for TDFN4 packages to Subcontractor UTAC in Thailand.

CLASSIFICATION OF CHANGE: Assembly Site

REASON FOR CHANGE: Additional Assembly Capacity

EXPECTED INFLUENCE ON PERFORMANCE/QUALITY/RELIABILITY: There will be no effect on performance, quality or reliability.

PRODUCT CATEGORY: ICs

PART NUMBERS AFFECTED:

SIP32401ADNP-T1GE4	SIP32409DNP-T1-GE4	SIP32431DNP3-T1GE4	SIP32448DNP-T1-GE4
SIP32402ADNP-T1GE4	SIP32411DNP-T1-GE4	SIP4282DNP3-T1GE4	SIP32449DNP-T1-GE4
SIP32408DNP-T1-GE4	SIP32501DNP-T1-GE4	SIP32441DNP-T1-GE4	SIP4282ADNP3-T1GE4

VISHAY BRAND(s): Vishay-Siliconix

TIME SCHEDULE: Shipment of products will begin June 3rd, 2017

SAMPLE AVAILABILITY: Please contact your regional Vishay Sales office for sample availability.

QUALIFICATION DATA: Additional data available upon request.

This PCN is for notification purposes only. Your response is not required. If you have any questions, please contact your local Vishay Sales Office.

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For further information, please contact your regional Vishay office.

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Procedure #